
2SC3336

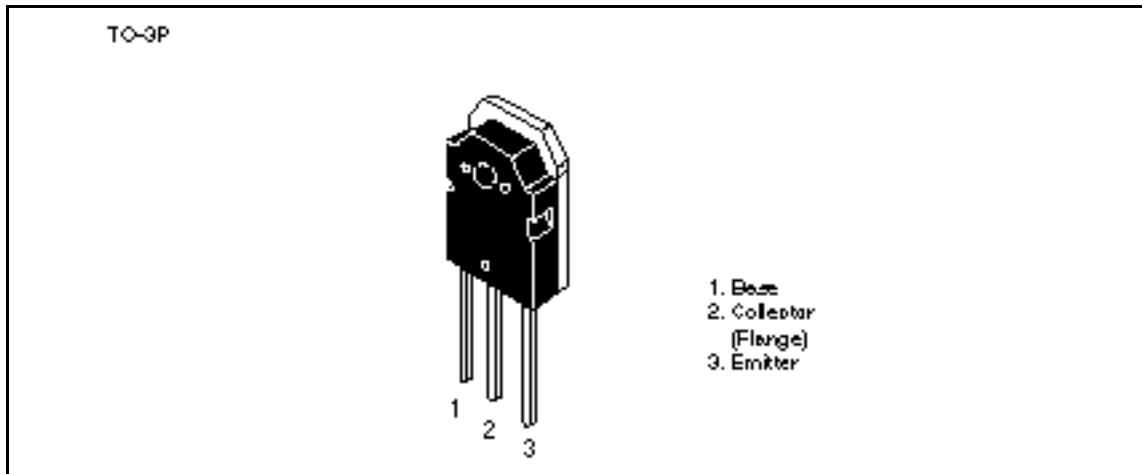
Silicon NPN Triple Diffused

HITACHI

Application

High voltage, high speed and high power switching

Outline



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Absolute Maximum Ratings (Ta = 25°C)

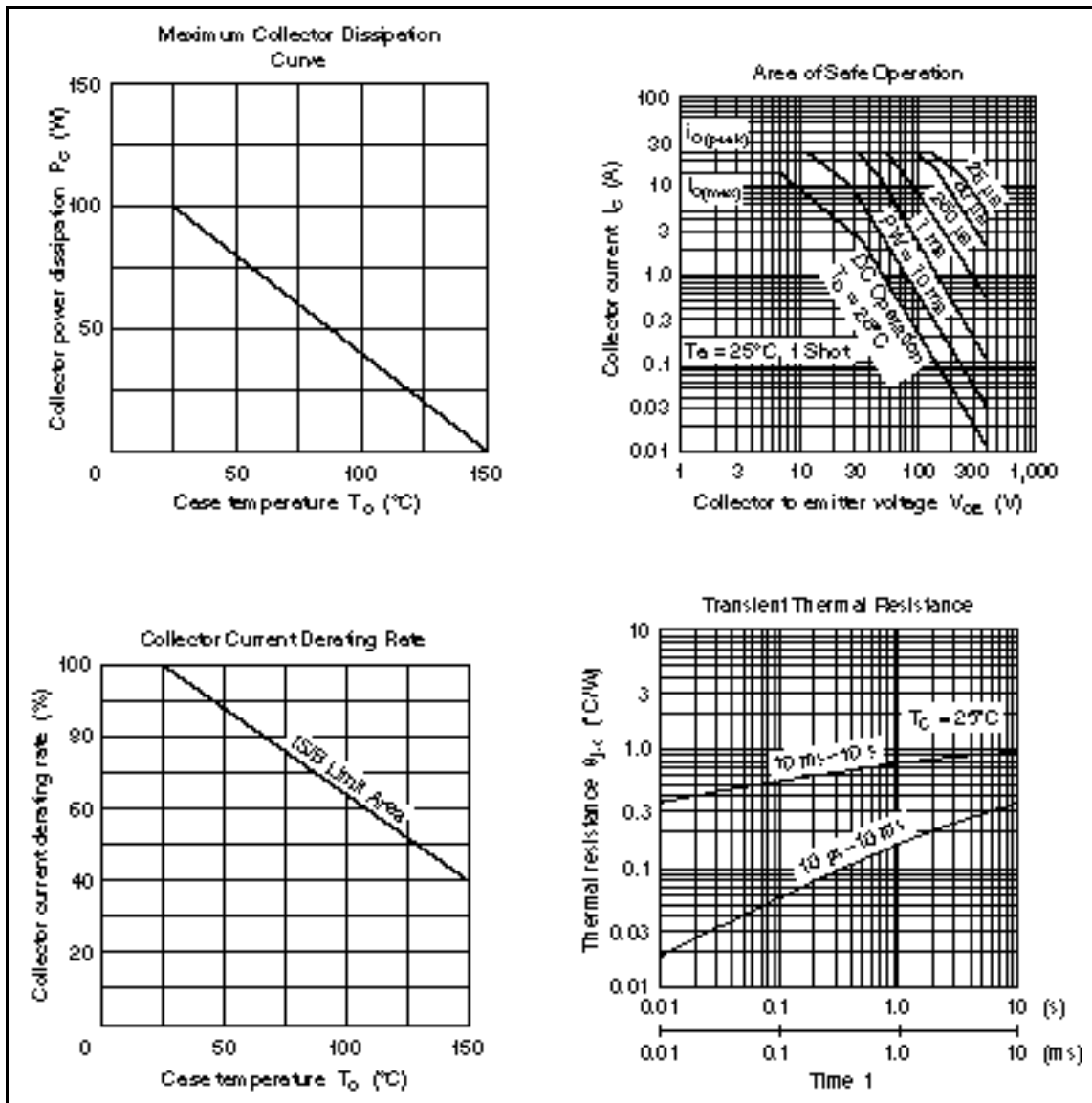
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	500	V
Collector to emitter voltage	V_{CEO}	400	V
Emitter to base voltage	V_{EBO}	10	V
Collector current	I_C	15	A
Collector peak current	$I_{C(peak)}$	25	A
Base current	I_B	7.5	A
Collector power dissipation	P_C^{*1}	100	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

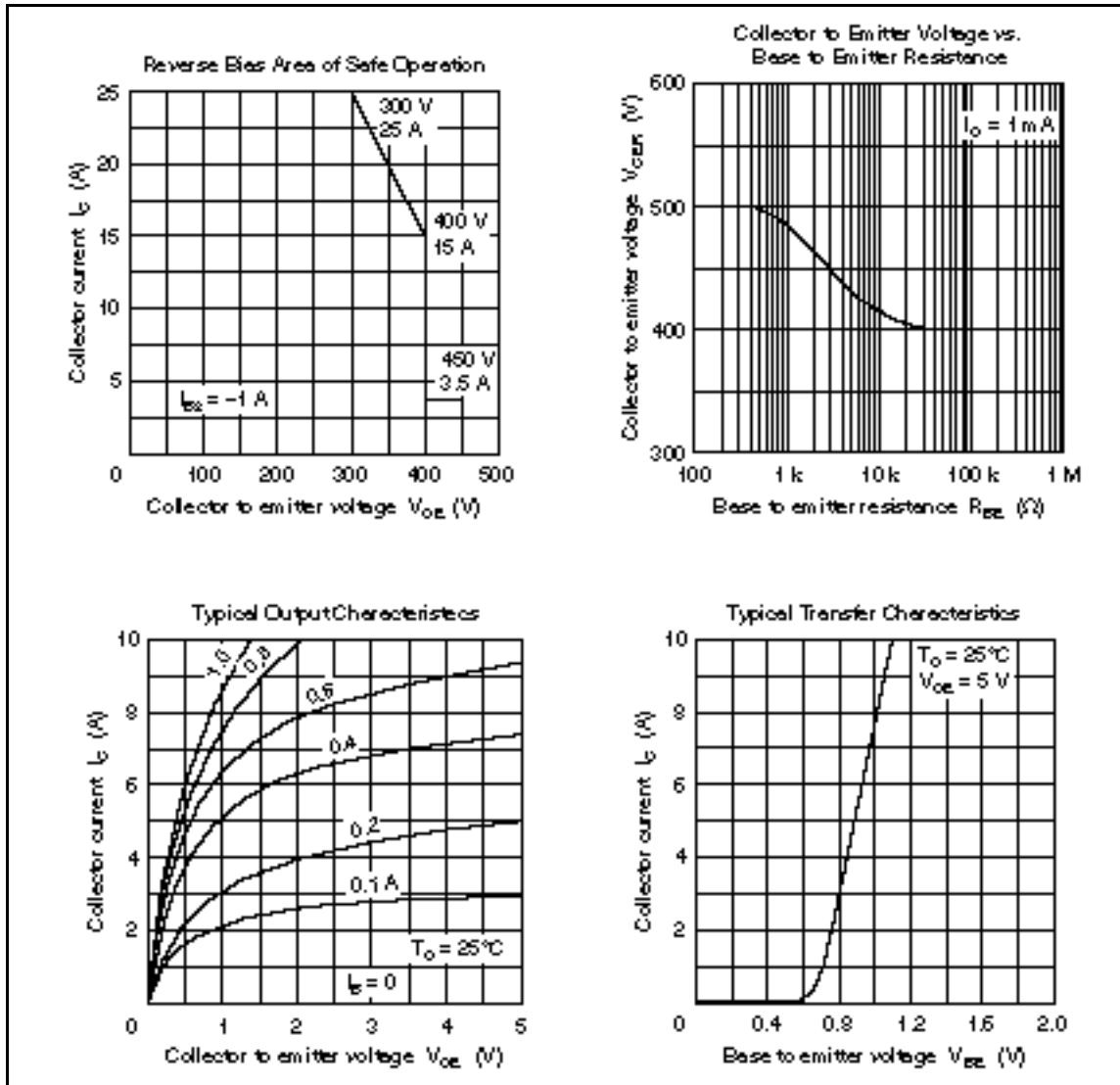
Note: 1. Value at $T_c = 25^\circ\text{C}$

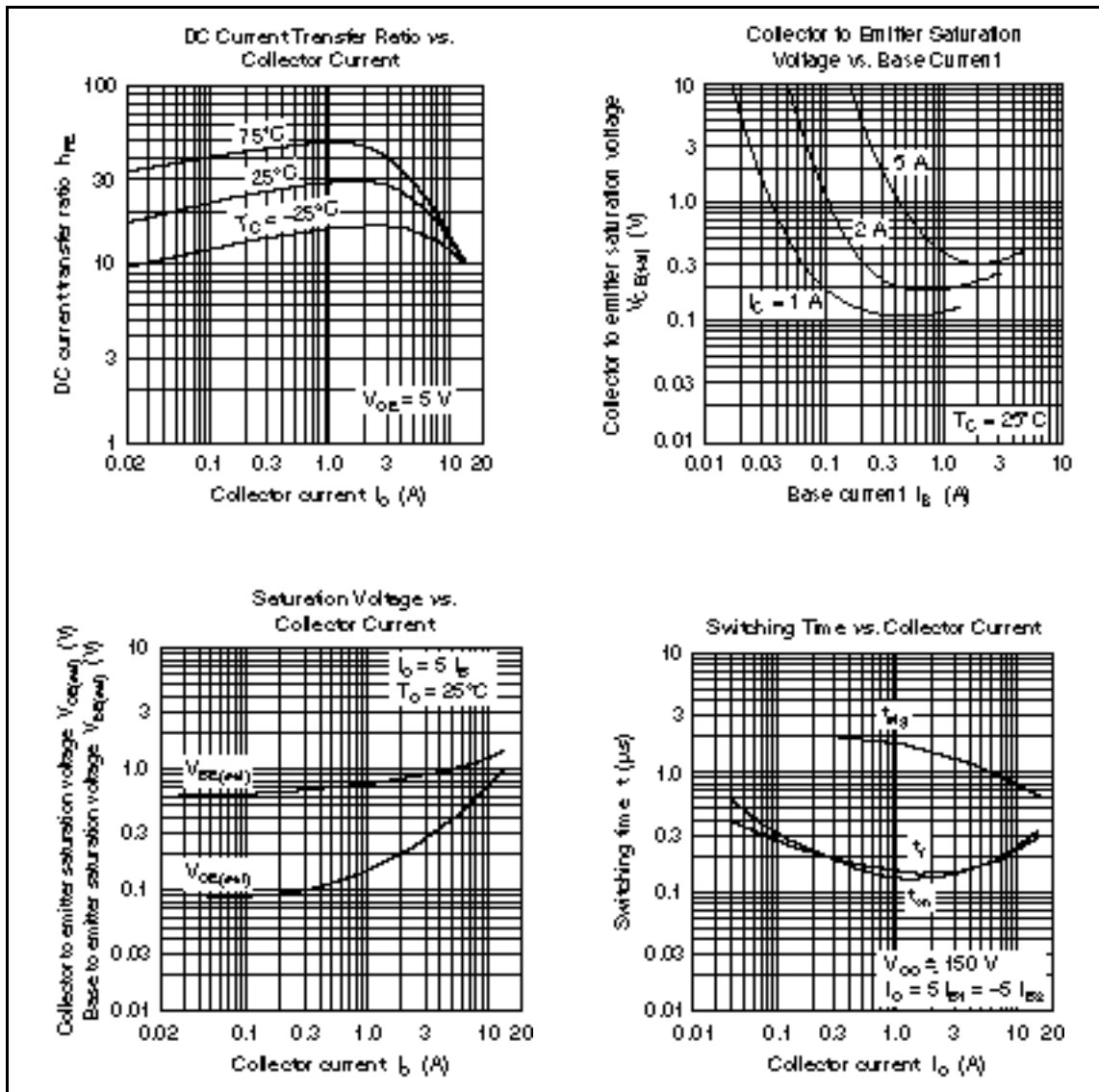
Electrical Characteristics (Ta = 25°C)

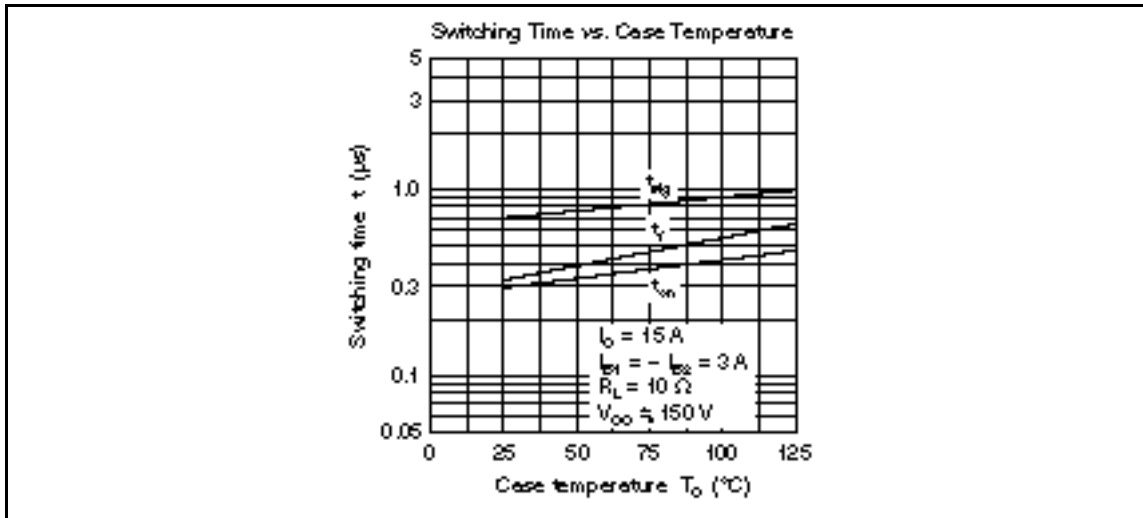
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to emitter sustain voltage	$V_{CEO(sus)}$	400	—	—	V	$I_C = 0.2\text{ A}$, $R_{BE} =$, $L = 100\text{ mH}$
	$V_{CEX(sus)}$	400	—	—	V	$I_C = 15\text{ A}$, $I_{B1} = 3.0\text{ A}$, $I_{B2} = -1\text{ A}$ $V_{BE} = -5.0\text{ V}$, $L = 180\text{ }\mu\text{H}$, Clamped
Emitter to base breakdown voltage	$V_{(BR)EBO}$	10	—	—	V	$I_E = 10\text{ mA}$, $I_C = 0$
Collector cutoff current	I_{CBO}	—	—	50	μA	$V_{CB} = 400\text{ V}$, $I_E = 0$
	I_{CEO}	—	—	50	μA	$V_{CE} = 350\text{ V}$, $R_{BE} =$
DC current transfer ratio	h_{FE1}	12	—	—		$V_{CE} = 5.0\text{ V}$, $I_C = 7.5\text{ A}^{*1}$
	h_{FE2}	5	—	—		$V_{CE} = 5.0\text{ V}$, $I_C = 15\text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	1.0	V	$I_C = 7.5\text{ A}$, $I_B = 1.5\text{ A}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)}$	—	—	1.5	V	
Turn on time	t_{on}	—	—	0.5	μs	$I_C = 15\text{ A}$, $I_{B1} = -I_{B2} = 3.0\text{ A}$
Storage time	t_{stg}	—	—	1.5	μs	$V_{CC} = 150\text{ V}$
Fall time	t_f	—	0.3	0.5	μs	

Note: 1. Pulse test









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